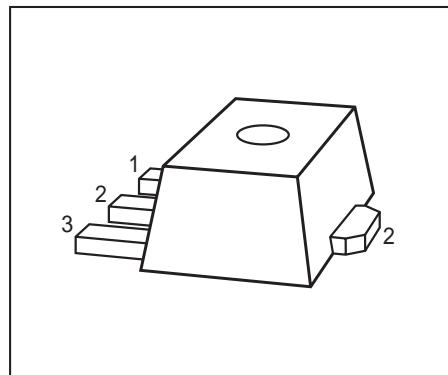


NPN Silicon Darlington Transistors

- For general AF applications
- High collector current
- High current gain
- Complementary types: BCV28, BCV48 (PNP)
- Pb-free (RoHS compliant) package¹⁾
- Qualified according AEC Q101



Type	Marking	Pin Configuration			Package
BCV29	EF	1=B	2=C	3=E	SOT89
BCV49	EG	1=B	2=C	3=E	SOT89

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-emitter voltage BCV29	V_{CEO}	30	V
BCV49		60	
Collector-base voltage BCV29	V_{CBO}	40	
BCV49		80	
Emitter-base voltage	V_{EBO}	10	
Collector current	I_C	500	mA
Peak collector current	I_{CM}	800	
Base current	I_B	100	
Peak base current	I_{BM}	200	
Total power dissipation- $T_S \leq 130^\circ\text{C}$	P_{tot}	1	W
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-65 ... 150	

¹Pb-containing package may be available upon special request

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R_{thJS}	≤ 20	K/W

¹⁾For calculation of R_{thJA} please refer to Application Note Thermal Resistance

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
DC Characteristics					
Collector-emitter breakdown voltage $I_C = 10 \text{ mA}, I_B = 0$, BCV29 $I_C = 10 \text{ mA}, I_B = 0$, BCV49	$V_{(\text{BR})\text{CEO}}$	30 60	- -	- -	V
Collector-base breakdown voltage $I_C = 100 \mu\text{A}, I_E = 0$, BCV29 $I_C = 100 \mu\text{A}, I_E = 0$, BCV49	$V_{(\text{BR})\text{CBO}}$	40 80	- -	- -	
Emitter-base breakdown voltage $I_E = 10 \mu\text{A}, I_C = 0$	$V_{(\text{BR})\text{EBO}}$	10	-	-	
Collector-base cutoff current $V_{CB} = 30 \text{ V}, I_E = 0$, BCV29 $V_{CB} = 60 \text{ V}, I_E = 0$, BCV49 $V_{CB} = 30 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$, BCV29 $V_{CB} = 60 \text{ V}, I_E = 0, T_A = 150^\circ\text{C}$, BCV49	I_{CBO}	- - - -	- - - -	0.1 0.1 10 10	μA
Emitter-base cutoff current $V_{EB} = 4 \text{ V}, I_C = 0$	I_{EBO}	-	-	100	nA
DC current gain ¹⁾ $I_C = 100 \mu\text{A}, V_{CE} = 1 \text{ V}$, BCV29 $I_C = 100 \mu\text{A}, V_{CE} = 1 \text{ V}$, BCV49 $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}$, BCV29 $I_C = 10 \text{ mA}, V_{CE} = 5 \text{ V}$, BCV49 $I_C = 100 \text{ mA}, V_{CE} = 5 \text{ V}$, BCV29 $I_C = 100 \text{ mA}, V_{CE} = 5 \text{ V}$, BCV49 $I_C = 0.5 \text{ A}, V_{CE} = 5 \text{ V}$, BCV29 $I_C = 0.5 \text{ A}, V_{CE} = 5 \text{ V}$, BCV49	h_{FE}	4000 2000 10000 4000 20000 10000 4000 2000	- - - - - - - -	- - - - - - - -	-
Collector-emitter saturation voltage ¹⁾ $I_C = 100 \text{ mA}, I_B = 0.1 \text{ mA}$	V_{CEsat}	-	-	1	V
Base emitter saturation voltage ¹⁾ $I_C = 100 \text{ mA}, I_B = 0.1 \text{ mA}$	V_{BEsat}	-	-	1.5	

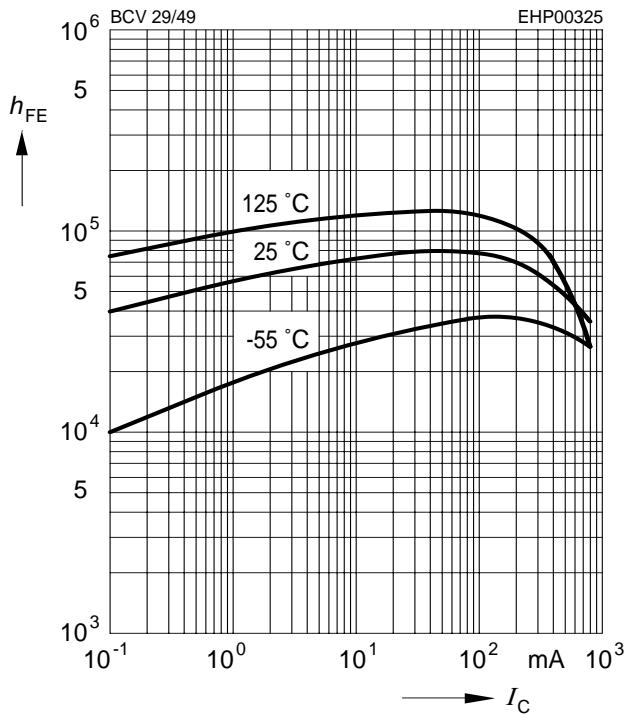
¹⁾Pulse test: $t < 300\mu\text{s}$; $D < 2\%$

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
AC Characteristics					
Transition frequency $I_C = 50 \text{ mA}, V_{CE} = 5 \text{ V}, f = 100 \text{ MHz}$	f_T	-	150	-	MHz
Collector-base capacitance $V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$	C_{cb}	-	3	-	pF

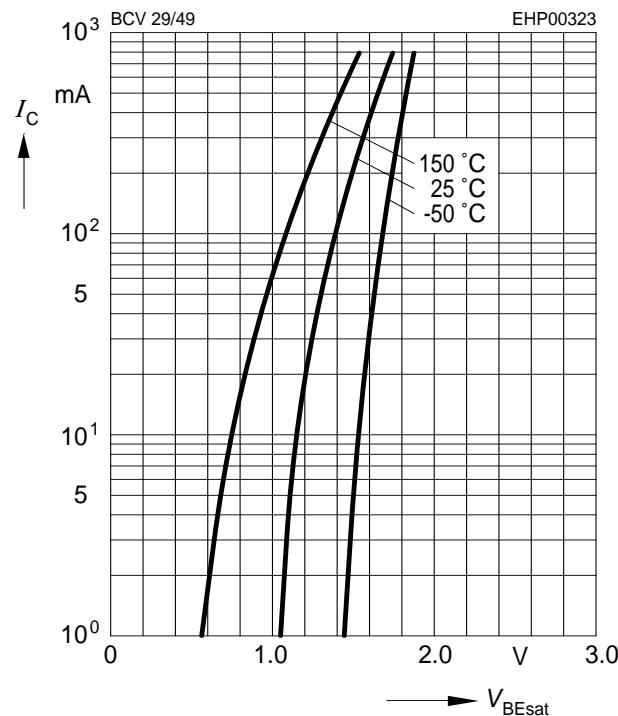
DC current gain $h_{FE} = f(I_C)$

$V_{CE} = 5 \text{ V}$



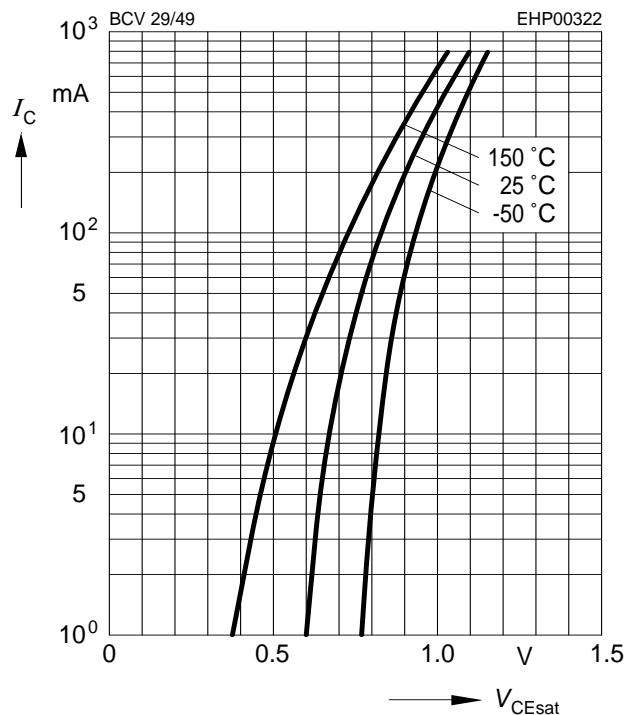
Base-emitter saturation voltage

$I_C = f(V_{BEsat})$, $h_{FE} = 1000$



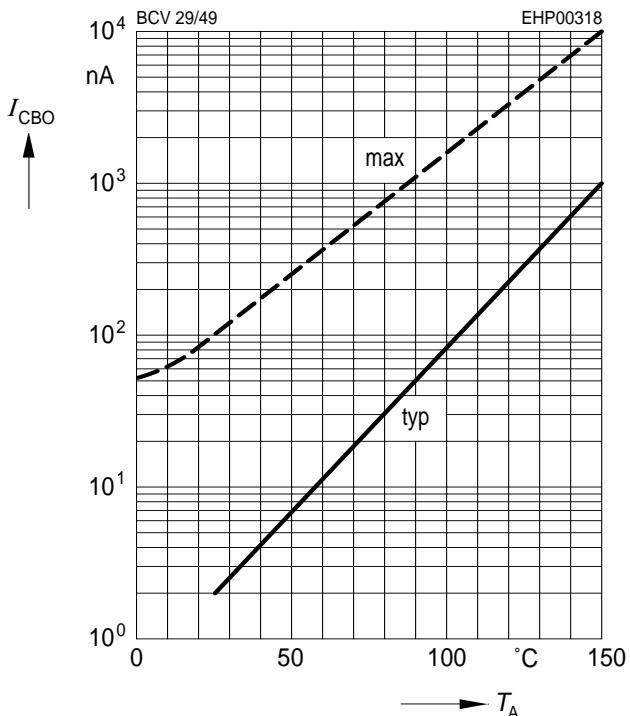
Collector-emitter saturation voltage

$I_C = f(V_{CEsat})$, $h_{FE} = 1000$

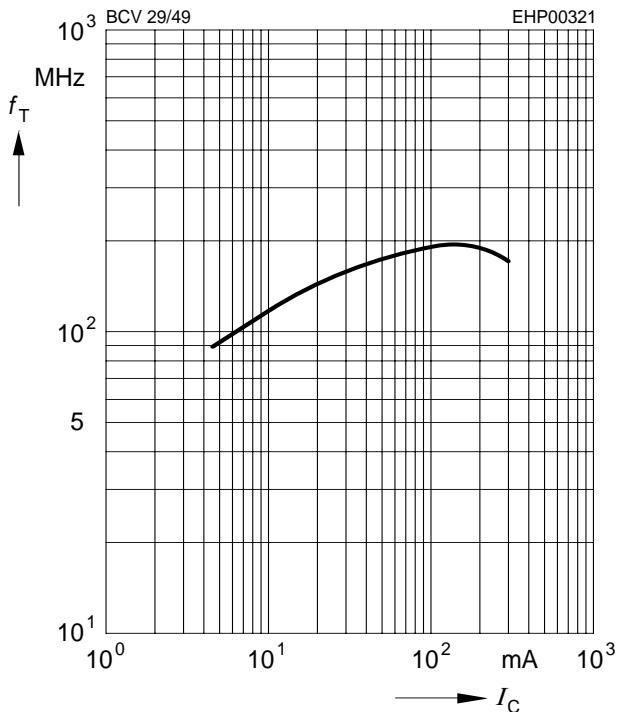


Collector cutoff current $I_{CBO} = f(T_A)$

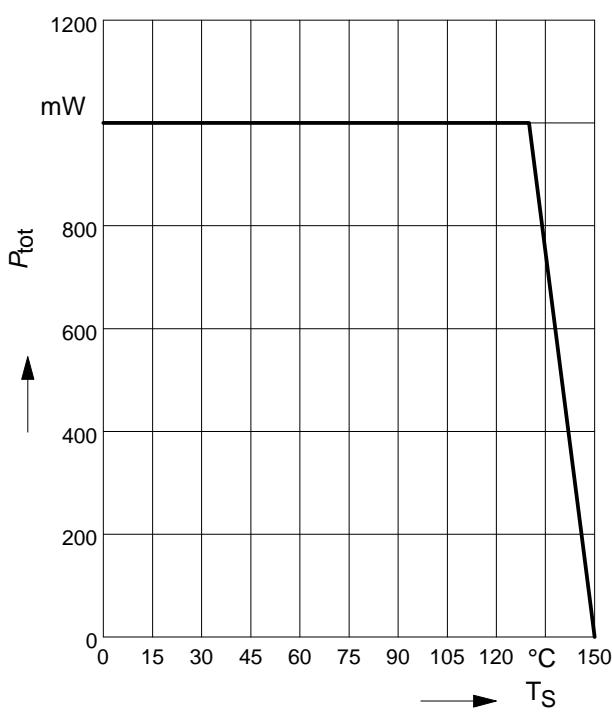
$V_{CB} = V_{CEmax}$



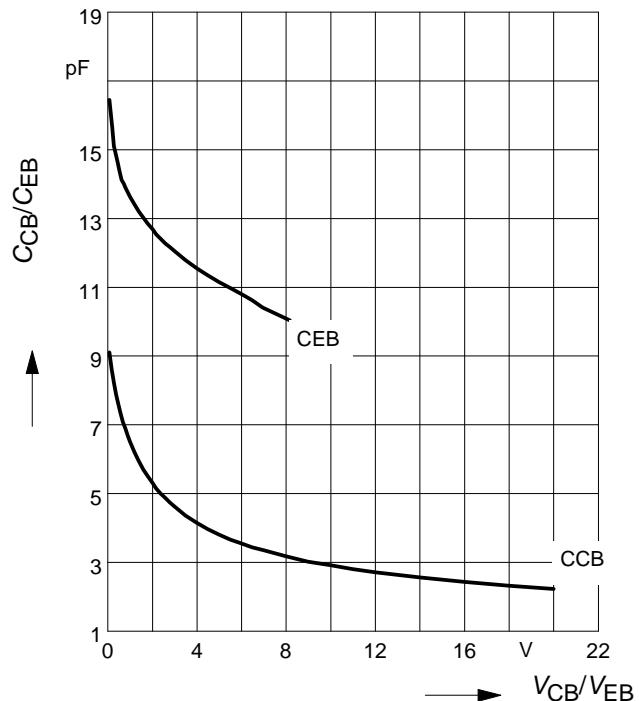
Transition frequency $f_T = f(I_C)$
 $V_{CE} = 5 \text{ V}$



Total power dissipation $P_{\text{tot}} = f(T_S)$

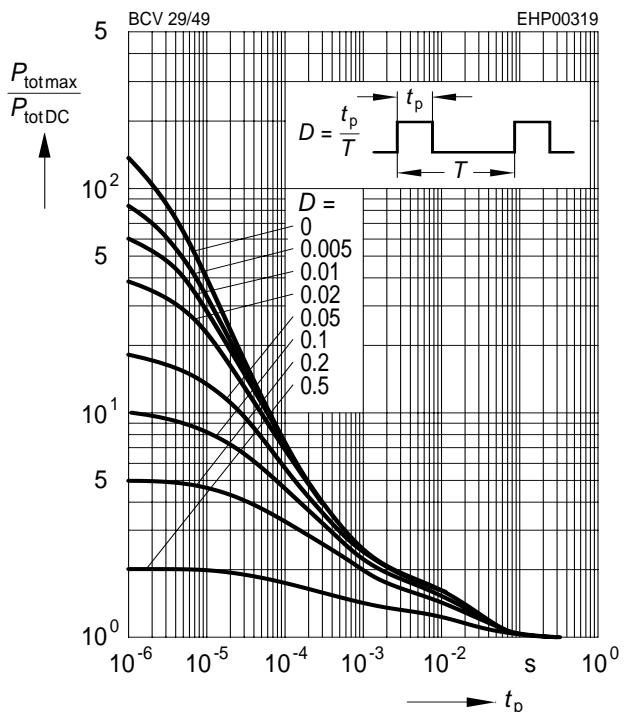


Collector-base capacitance $C_{cb} = f(V_{CB})$
Emitter-base capacitance $C_{eb} = f(V_{EB})$

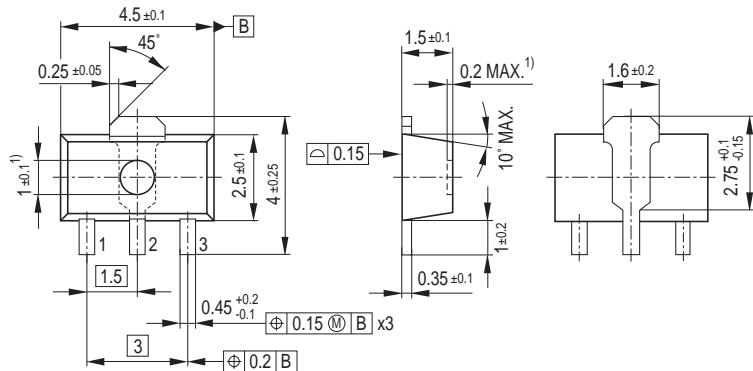
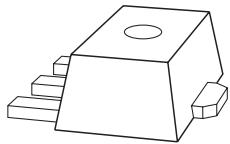


Permissible Pulse Load

$P_{\text{totmax}}/P_{\text{totDC}} = f(t_p)$

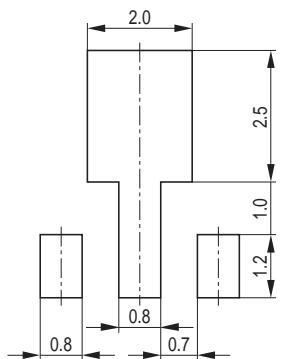


Package Outline

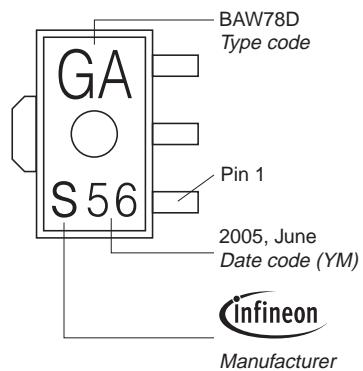


1) Ejector pin markings possible

Foot Print

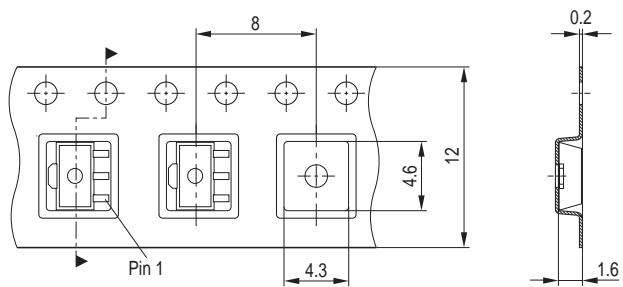


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 1.000 Pieces/Reel
Reel ø330 mm = 4.000 Pieces/Reel



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